

Material Composition Specification

DO-201 Case

Available with Pb (lead)-free plating*



Device average mass 945 mg

Fluctuation margin +/-10%

Device part	Substance	mass (mg)
active device	doped Si	3.20
leadframe	Copper alloy	629
die attach	Pb92.5Ag2.5Sn5	2.05
*plating	SnPb20	7.76
	or Sn (100% tin, Pb-free)	7.76
encapsulation	epoxy molding compound -silica -epoxy < 20% -resin < 10% -Sb ₂ O ₃ < 1.0%	303

* specify Lead-free when ordering 100% tin (Pb-free) plating option.